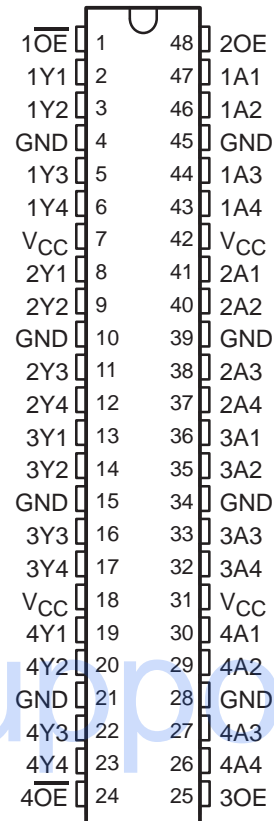


SN54ABT16241A, SN74ABT16241A 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS096G – FEBRUARY 1991 – REVISED OCTOBER 1998

- Members of the Texas Instruments *Widebus™* Family
- State-of-the-Art *EPIC-II B™* BiCMOS Design Significantly Reduces Power Dissipation
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs ($-32\text{-mA } I_{OH}$, $64\text{-mA } I_{OL}$)
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model ($C = 200$ pF, $R = 0$)
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

SN54ABT16241A . . . WD PACKAGE
SN74ABT16241A . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The 'ABT16241A devices are 16-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide true outputs and complementary output-enable (OE and \overline{OE}) inputs.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT16241A is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABT16241A is characterized for operation from -40°C to 85°C .



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54ABT16241A, SN74ABT16241A

16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

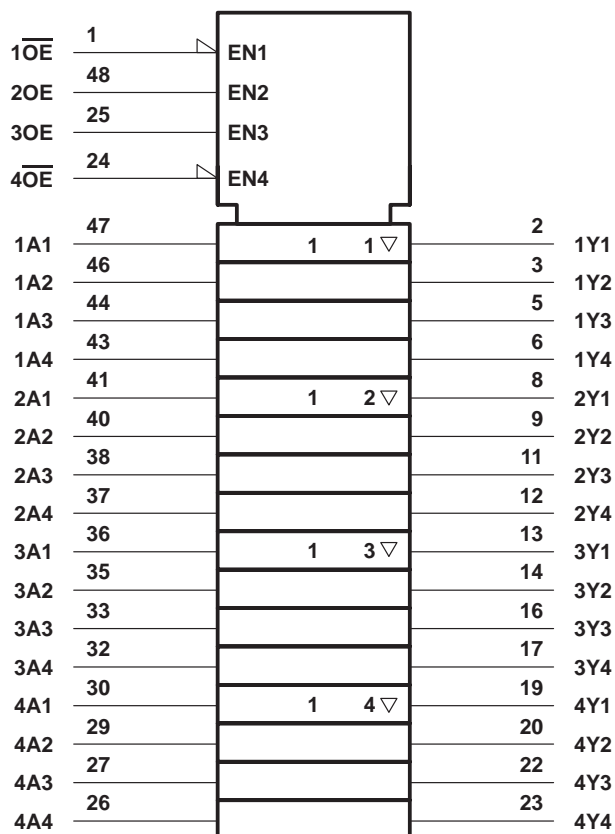
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FUNCTION TABLES

| INPUTS | | OUTPUTS |
|----------|--------|---------|
| 1OE, 4OE | 1A, 4A | 1Y, 4Y |
| L | H | H |
| L | L | L |
| H | X | Z |

| INPUTS | | OUTPUTS |
|----------|--------|---------|
| 2OE, 3OE | 2A, 3A | 2Y, 3Y |
| H | H | H |
| H | L | L |
| L | X | Z |

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

SN54ABT16241A, SN74ABT16241A

16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

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recommended operating conditions (see Note 3)

| | | SN54ABT16241A | | SN74ABT16241A | | UNIT |
|-----------------|------------------------------------|-----------------|-----------------|---------------|-----------------|------|
| | | MIN | MAX | MIN | MAX | |
| V _{CC} | Supply voltage | 4.5 | 5.5 | 4.5 | 5.5 | V |
| V _{IH} | High-level input voltage | 2 | | 2 | | V |
| V _{IL} | Low-level input voltage | | 0.8 | | 0.8 | V |
| V _I | Input voltage | 0 | V _{CC} | 0 | V _{CC} | V |
| I _{OH} | High-level output current | | -24 | | -32 | mA |
| I _{OL} | Low-level output current | | 48 | | 64 | mA |
| Δt/Δv | Input transition rise or fall rate | Outputs enabled | | 10 | 10 | ns/V |
| T _A | Operating free-air temperature | -55 | 125 | -40 | 85 | °C |

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | T _A = 25°C | | | SN54ABT16241A | | SN74ABT16241A | | UNIT | |
|--------------------------|--|---|------------------|-------|---------------|------|---------------|------|------|----|
| | | MIN | TYP† | MAX | MIN | MAX | MIN | MAX | | |
| V _{IK} | V _{CC} = 4.5 V, I _I = -18 mA | | | -1.2 | | -1.2 | | -1.2 | V | |
| V _{OH} | V _{CC} = 4.5 V, I _{OH} = -3 mA | 2.5 | | | 2.5 | | 2.5 | | V | |
| | V _{CC} = 5 V, I _{OH} = -3 mA | 3 | | | 3 | | 3 | | | |
| | V _{CC} = 4.5 V | I _{OH} = -24 mA | 2 | | | 2 | | | | |
| I _{OH} = -32 mA | | 2* | | | | | 2 | | | |
| V _{OL} | V _{CC} = 4.5 V | I _{OL} = 48 mA | | 0.55 | | 0.55 | | | V | |
| | | I _{OL} = 64 mA | | 0.55* | | | 0.55 | | | |
| V _{hys} | | | 100 | | | | | mV | | |
| I _I | V _{CC} = 5.5 V, V _I = V _{CC} or GND | | | ±1 | | ±1 | | ±1 | μA | |
| I _{OZH} | V _{CC} = 5.5 V, V _O = 2.7 V | | | 10 | | 10 | | 10 | μA | |
| I _{OZL} | V _{CC} = 5.5 V, V _O = 0.5 V | | | -10 | | -10 | | -10 | μA | |
| I _{off} | V _{CC} = 0, V _I or V _O ≤ 4.5 V | | | ±100 | | | | ±100 | μA | |
| I _{CEX} | V _{CC} = 5.5 V, V _O = 5.5 V | Outputs high | | 50 | | 50 | | 50 | μA | |
| I _{O‡} | V _{CC} = 5.5 V, V _O = 2.5 V | -50 | -100 | -180 | -50 | -180 | -50 | -180 | mA | |
| I _{CC} | V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND | Outputs high | | 3 | | 3 | | 3 | mA | |
| | | Outputs low | | 34 | | 34 | | 34 | | |
| | | Outputs disabled | | 3 | | 3 | | 3 | | |
| ΔI _{CC} § | Data inputs | V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND | Outputs enabled | | 1 | | 1.5 | | 1 | mA |
| | | | Outputs disabled | | 0.05 | | 1 | | 0.05 | |
| | Control inputs | V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND | | 1.5 | | 1.5 | | 1.5 | | |
| C _i | V _I = 2.5 V or 0.5 V | | 3.5 | | | | | pF | | |
| C _o | V _O = 2.5 V or 0.5 V | | 7.5 | | | | | pF | | |

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V_{CC} = 5 V.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



SN54ABT16241A, SN74ABT16241A
16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | SN54ABT16241A | | | | UNIT | |
|-----------|-----------------------|-------------|---------------------------------------|-----|-----|-----|------|-----|
| | | | $V_{CC} = 5$ V, $T_A = 25^\circ$ C | | | MIN | | MAX |
| | | | MIN | TYP | MAX | | | |
| t_{PLH} | A | Y | 0.9 | 2.7 | 3.4 | 0.9 | 3.8 | ns |
| t_{PHL} | | | 0.9 | 2.7 | 3.9 | 0.9 | 4.6 | |
| t_{PZH} | OE or \overline{OE} | Y | 1.2 | 3.3 | 4.2 | 1.2 | 5.1 | ns |
| t_{PZL} | | | 1.3 | 3.4 | 5.9 | 1.3 | 7 | |
| t_{PHZ} | OE or \overline{OE} | Y | 1.5 | 4.1 | 5.5 | 1.5 | 7 | ns |
| t_{PLZ} | | | 1.7 | 3.6 | 5.1 | 1.7 | 5.7 | |

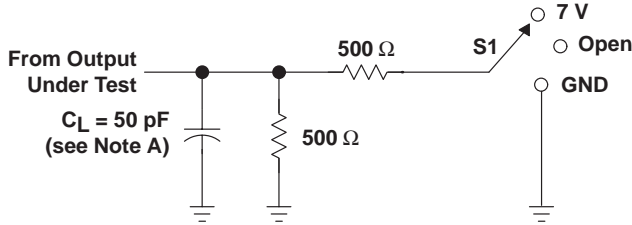
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | SN74ABT16241A | | | | UNIT | |
|-----------|-----------------------|-------------|---------------------------------------|-----|-----|-----|------|-----|
| | | | $V_{CC} = 5$ V, $T_A = 25^\circ$ C | | | MIN | | MAX |
| | | | MIN | TYP | MAX | | | |
| t_{PLH} | A | Y | 1 | 2.7 | 3.4 | 1 | 3.7 | ns |
| t_{PHL} | | | 1 | 2.7 | 3.9 | 1 | 4.5 | |
| t_{PZH} | OE or \overline{OE} | Y | 1.2 | 3.3 | 4.2 | 1.2 | 5 | ns |
| t_{PZL} | | | 1.3 | 3.4 | 5.9 | 1.3 | 6.9 | |
| t_{PHZ} | OE or \overline{OE} | Y | 1.5 | 4.1 | 5.2 | 1.5 | 6.2 | ns |
| t_{PLZ} | | | 1.7 | 3.6 | 5.1 | 1.7 | 5.6 | |

SN54ABT16241A, SN74ABT16241A
16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

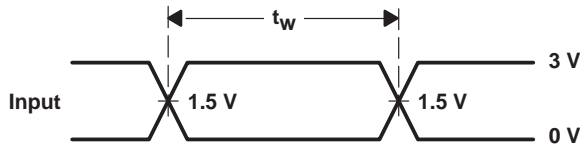
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PARAMETER MEASUREMENT INFORMATION

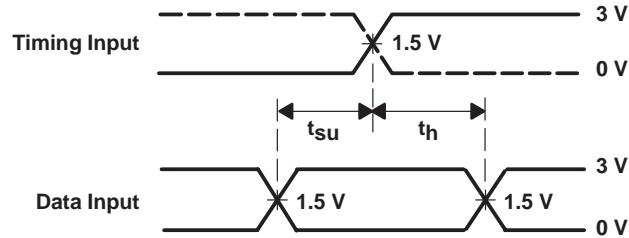


LOAD CIRCUIT

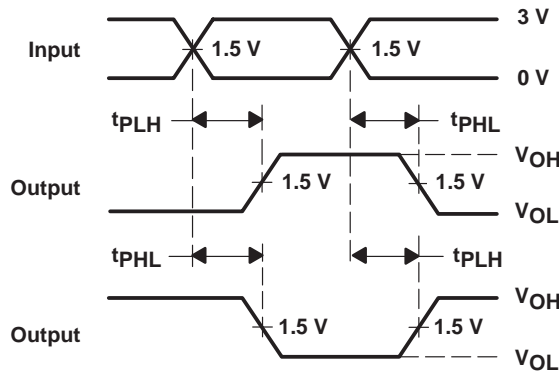
| TEST | S1 |
|-------------------|------|
| t_{PLH}/t_{PHL} | Open |
| t_{PLZ}/t_{PZL} | 7 V |
| t_{PHZ}/t_{PZH} | Open |



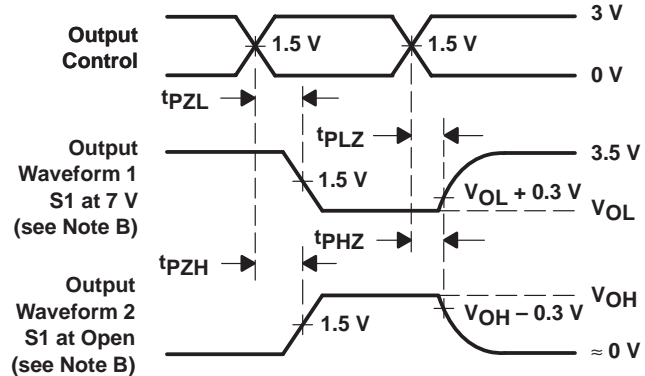
**VOLTAGE WAVEFORMS
 PULSE DURATION**



**VOLTAGE WAVEFORMS
 SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS
 PROPAGATION DELAY TIMES
 INVERTING AND NONINVERTING OUTPUTS**



**VOLTAGE WAVEFORMS
 ENABLE AND DISABLE TIMES
 LOW- AND HIGH-LEVEL ENABLING**

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|--------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 5962-9450101QXA | ACTIVE | CFP | WD | 48 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| 74ABT16241ADGGRE4 | ACTIVE | TSSOP | DGG | 48 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74ABT16241ADGVRE4 | ACTIVE | TVSOP | DGV | 48 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74ABT16241ADGVRG4 | ACTIVE | TVSOP | DGV | 48 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74ABT16241ADGGR | ACTIVE | TSSOP | DGG | 48 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74ABT16241ADGVR | ACTIVE | TVSOP | DGV | 48 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74ABT16241ADL | ACTIVE | SSOP | DL | 48 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74ABT16241ADLG4 | ACTIVE | SSOP | DL | 48 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74ABT16241ADLR | ACTIVE | SSOP | DL | 48 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74ABT16241ADLRG4 | ACTIVE | SSOP | DL | 48 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SNJ54ABT16241AWD | ACTIVE | CFP | WD | 48 | 1 | TBD | A42 SNPB | N / A for Pkg Type |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

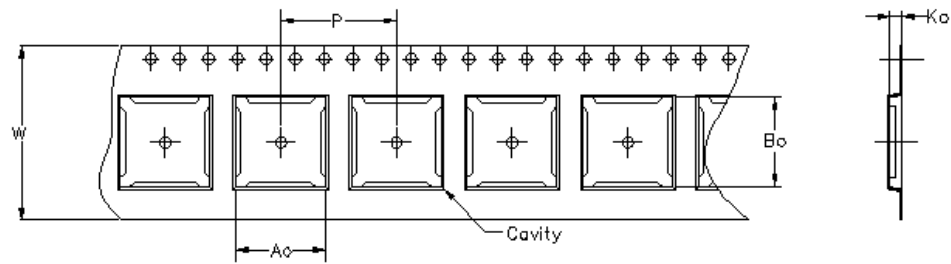
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

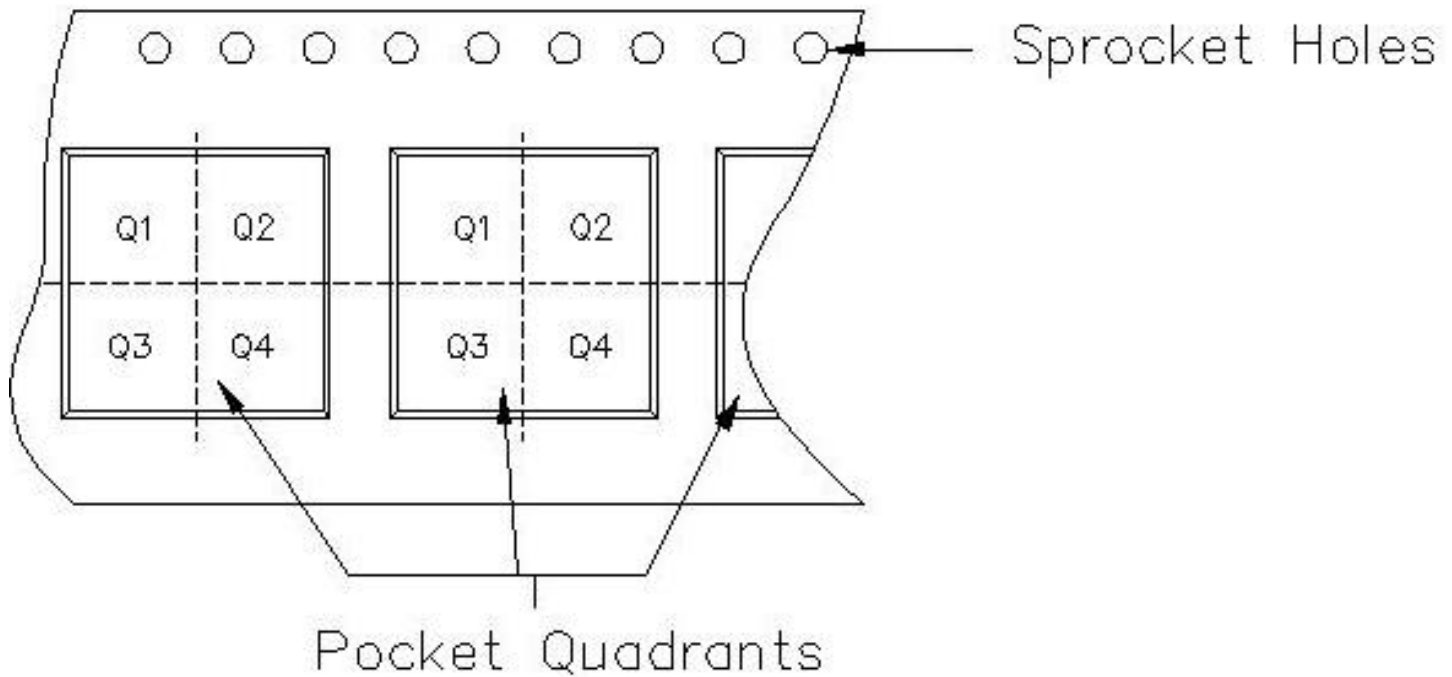
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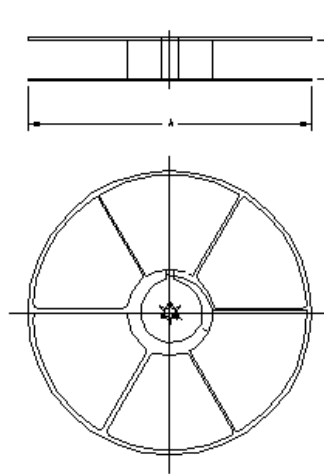
Carrier tape design is defined largely by the component length, width, and thickness.

| |
|--|
| A_o = Dimension designed to accommodate the component width. |
| B_o = Dimension designed to accommodate the component length. |
| K_o = Dimension designed to accommodate the component thickness. |
| W = Overall width of the carrier tape. |
| P = Pitch between successive cavity centers. |



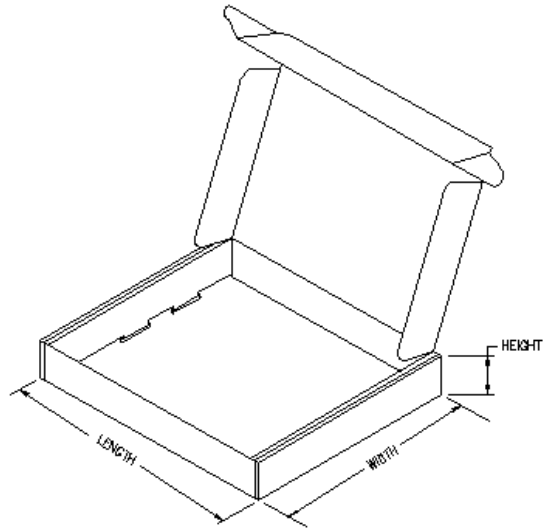
TAPE AND REEL INFORMATION

| Device | Package | Pins | Site | Reel Diameter (mm) | Reel Width (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------------|---------|------|------|--------------------|-----------------|---------|---------|---------|---------|--------|---------------|
| SN74ABT16241ADGGR | DGG | 48 | MLA | 330 | 24 | 8.6 | 15.8 | 1.8 | 12 | 24 | Q1 |
| SN74ABT16241ADGVR | DGV | 48 | MLA | 330 | 24 | 6.8 | 10.1 | 1.6 | 12 | 24 | Q1 |
| SN74ABT16241ADLR | DL | 48 | MLA | 330 | 32 | 11.35 | 16.2 | 3.1 | 16 | 32 | Q1 |



TAPE AND REEL BOX INFORMATION

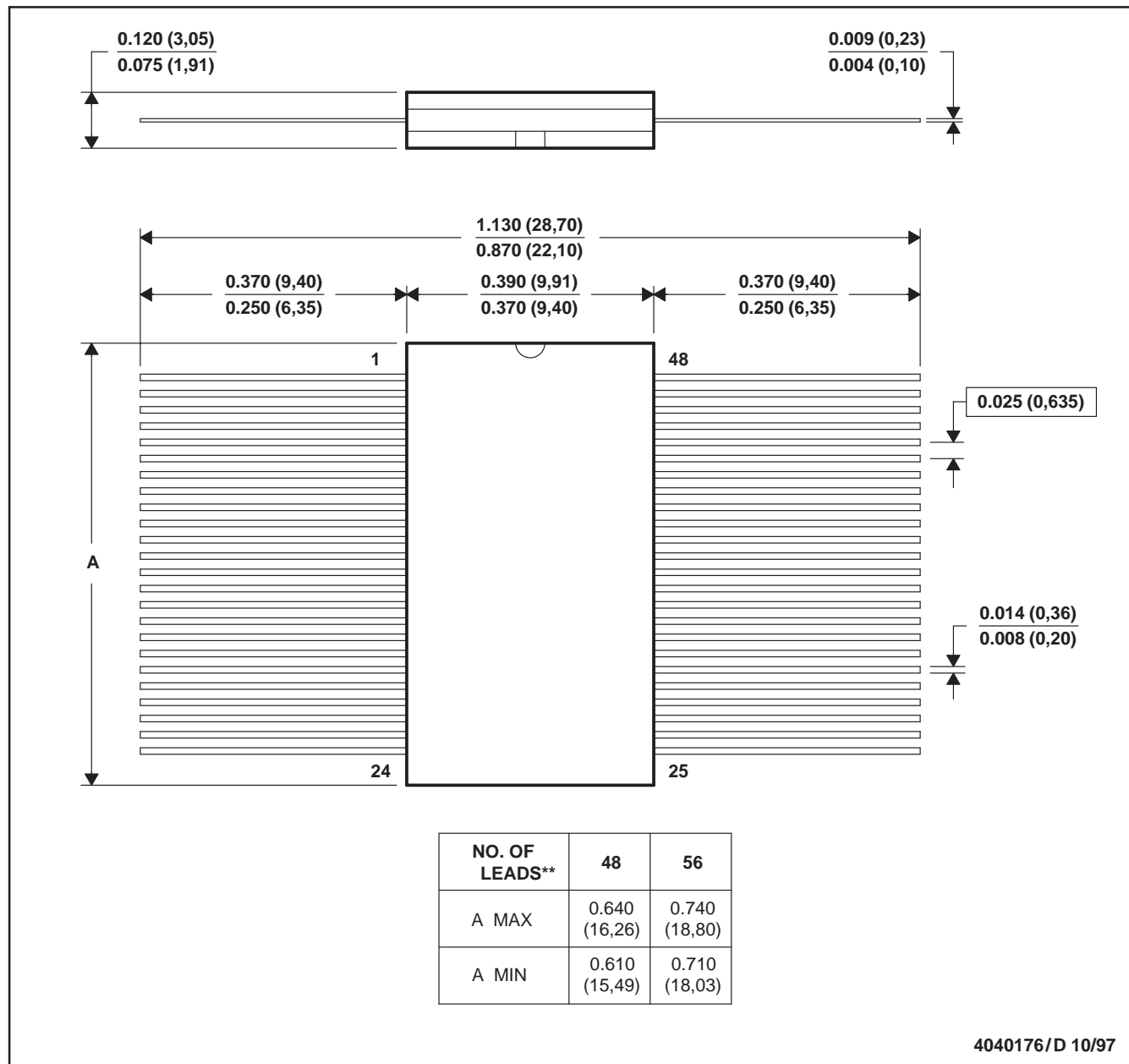
| Device | Package | Pins | Site | Length (mm) | Width (mm) | Height (mm) |
|-------------------|---------|------|------|-------------|------------|-------------|
| SN74ABT16241ADGGR | DGG | 48 | MLA | 333.2 | 333.2 | 31.75 |
| SN74ABT16241ADGVR | DGV | 48 | MLA | 333.2 | 333.2 | 31.75 |
| SN74ABT16241ADLR | DL | 48 | MLA | 346.0 | 346.0 | 49.0 |



WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only
 E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA
 GDFP1-F56 and JEDEC MO-146AB

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



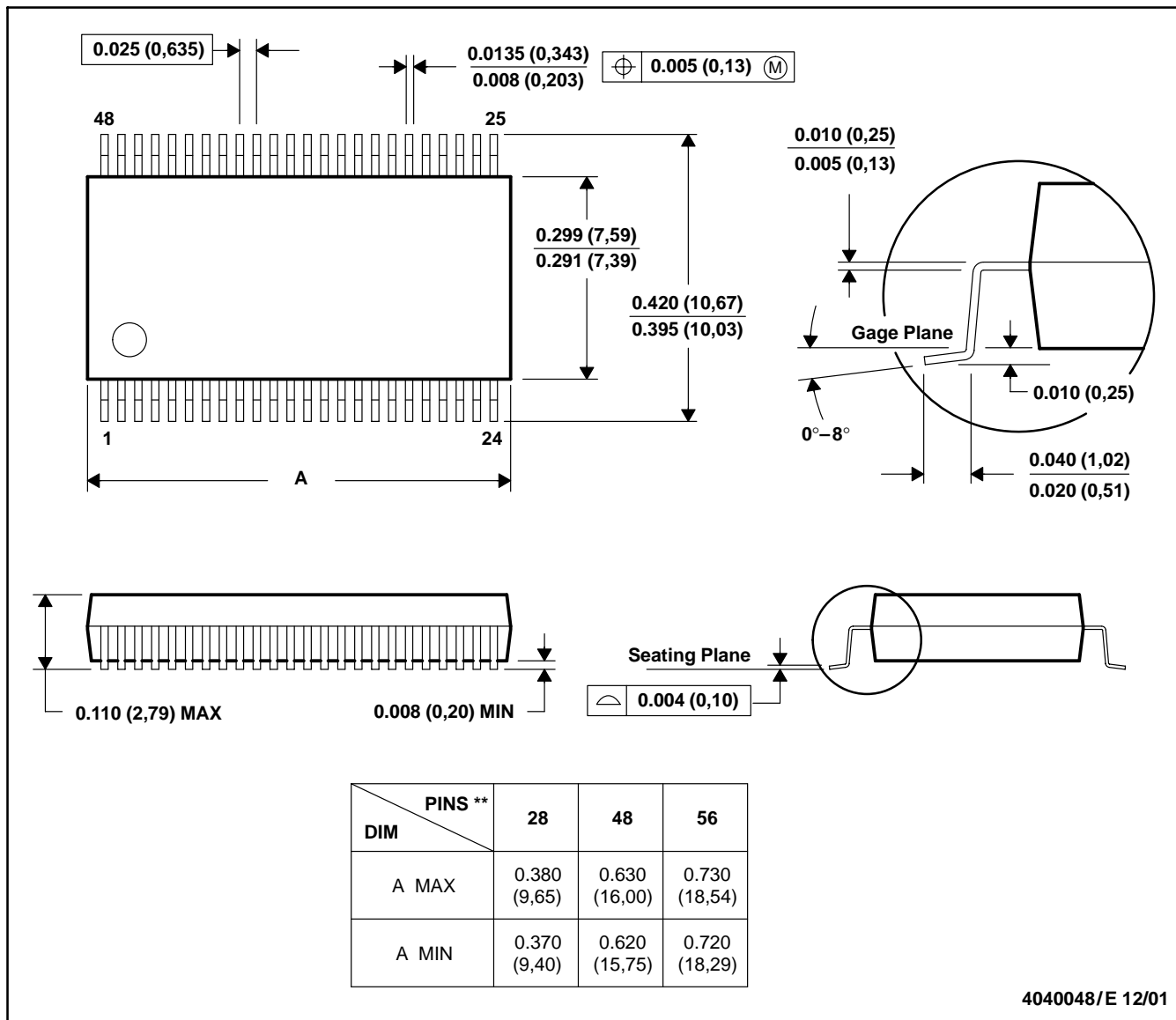
4073251/E 08/00

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

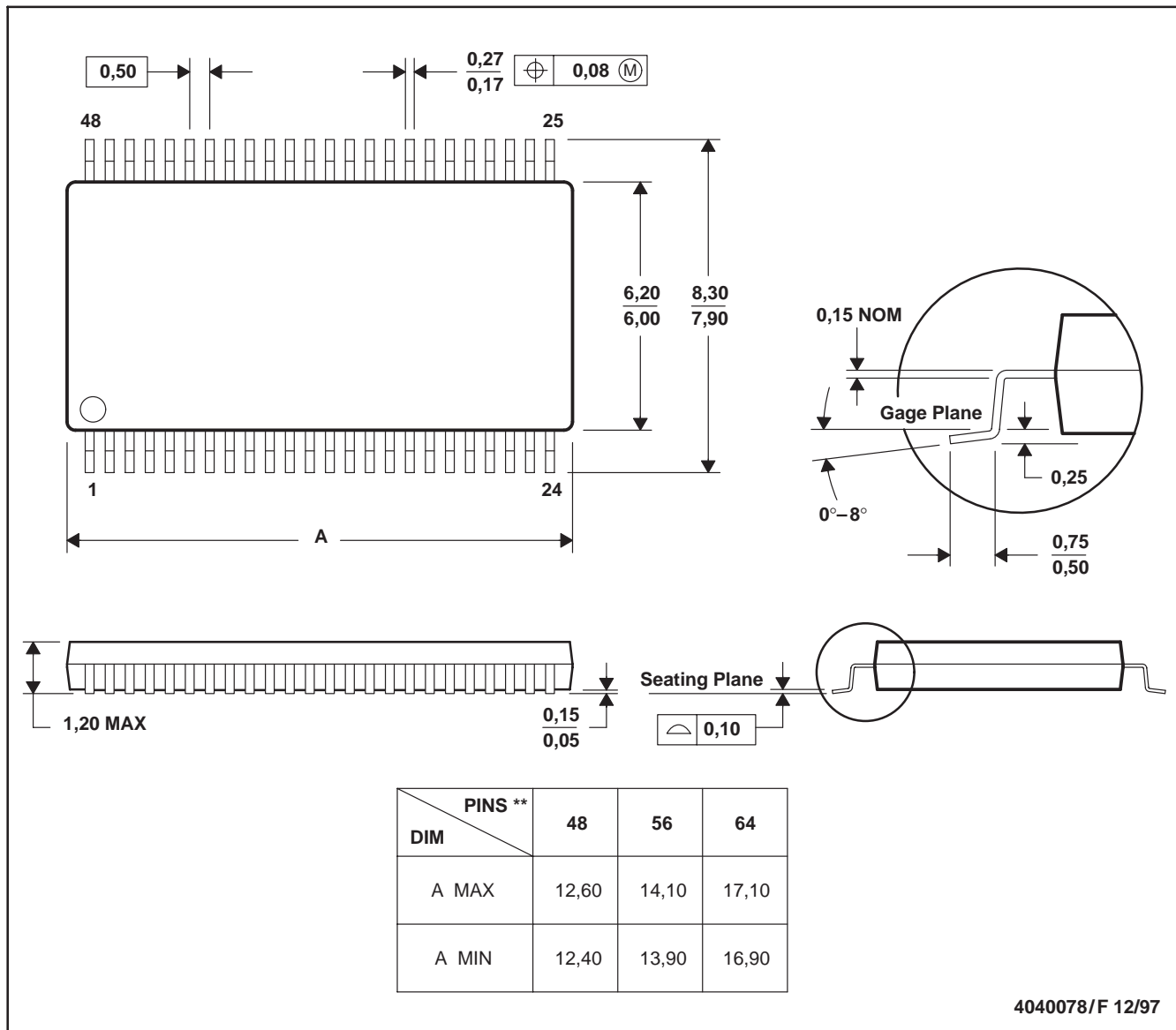


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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